

## Application Data Sheet

### Application Information

**Application Type::** Regular  
**Subject Matter::** Utility  
**Suggested classification::**  
**Suggested Group Art Unit::**  
**CD-ROM or CD-R?::** None  
**Computer Readable Form (CRF)?::** No  
**Title::** WAFER HEAT-TREATMENT SYSTEM AND  
WAFER HEAT-TREATMENT METHOD  
**Attorney Docket Number::** 025311-0115  
**Request for Early Publication?::** No  
**Request for Non-Publication?::** No  
**Suggested Drawing Figure::** 1  
**Total Drawing Sheets::** 3  
**Small Entity?::** No  
**Petition included?::** No  
**Secrecy Order in Parent Appl.?::** No

### Applicant Information

**Applicant Authority Type::** Inventor  
**Primary Citizenship Country::** Japanese  
**Status::** Full Capacity  
**Given Name::** Yoshimasa  
**Family Name::** KAWASE  
**City of Residence::** Kanagawa  
**Country of Residence::** Japan

**Street of mailing address::** c/o Semiconductor Leading Edge Technologies, Inc.  
292 Yoshida-cho, Totsuka-ku, Yokohama  
Kanagawa 244-0817, Japan

**Country of mailing address::** Japan

### Correspondence Information

**Correspondence Customer Number::** 22428

**E-Mail address::** wellis@foleylaw.com

### Representative Information

<b>Representative Customer Number::</b>	22428	
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### Domestic Priority Information

<b>Application::</b>	<b>Continuity Type::</b>	<b>Parent Application::</b>	<b>Parent Filing Date::</b>

### Foreign Priority Information

<b>Country::</b>	<b>Application number::</b>	<b>Filing Date::</b>	<b>Priority Claimed::</b>
Japan	2001-036040	02/13/2001	Yes

### Assignee Information

**Assignee name::** SEMICONDUCTOR LEADING EDGE  
TECHNOLOGIES, INC.